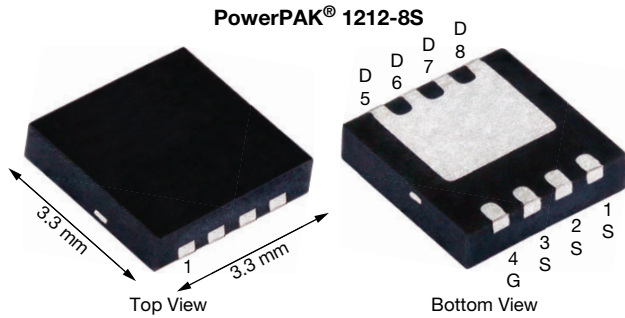


P-Channel 20 V (D-S) MOSFET



FEATURES

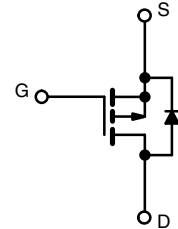
- TrenchFET® Gen III p-channel power MOSFET
- Leadership $R_{DS(on)}$ in compact and thermally enhanced package
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Battery management
- Load switch



P-Channel MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	-20
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5$ V	0.0027
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -2.5$ V	0.0036
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -1.8$ V	0.0070
Q_g typ. (nC)	72.2
I_D (A)	-127.5
Configuration	Single

ORDERING INFORMATION	
Package	PowerPAK 1212-8S
Lead (Pb)-free and halogen-free	SiSS63DN-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	-20	V
Gate-source voltage		V_{GS}	± 12	V
Continuous drain current ($T_J = 150$ °C)	$T_C = 25$ °C	I_D	-127.5	A
	$T_C = 70$ °C		-102	
	$T_A = 25$ °C		-35.1 ^{b, c}	
	$T_A = 70$ °C		-28.1	
Pulsed drain current ($t = 100$ μ s)		I_{DM}	-200	A
Continuous source-drain diode current	$T_C = 25$ °C	I_S	-54.8	A
	$T_A = 25$ °C		-4.2 ^{b, c}	
Single pulse avalanche current	L = 0.1 mH	I_{AS}	-25	mJ
Single pulse avalanche energy		E_{AS}	31.2	
Maximum power dissipation	$T_C = 25$ °C	P_D	65.8	W
	$T_C = 70$ °C		42.1	
	$T_A = 25$ °C		5 ^{b, c}	
	$T_A = 70$ °C		3.2 ^{b, c}	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^c			260	°C

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	$t \leq 10$ s	R_{thJA}	20	25	°C/W
Maximum junction-to-case (drain)	Steady state	R_{thJC}	1.5	1.9	

Notes

- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 65 °C/W



SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = -250\text{ }\mu\text{A}$	-20	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = -10\text{ mA}$	-	-15	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250\text{ }\mu\text{A}$	-	4	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\text{ }\mu\text{A}$	-0.5	-	-1.5	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 12\text{ V}$	-	-	100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -20\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	-1	μA
		$V_{DS} = -20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 70\text{ }^\circ\text{C}$	-	-	-15	
On-state drain current ^a	$I_{D(on)}$	$V_{DS} \geq -10\text{ V}$, $V_{GS} = -10\text{ V}$	-20	-	-	A
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$, $I_D = -15\text{ A}$	-	0.0022	0.0027	Ω
		$V_{GS} = -4.5\text{ V}$, $I_D = -10\text{ A}$	-	0.0030	0.0036	
		$V_{GS} = -2.5\text{ V}$, $I_D = -5\text{ A}$	-	0.0053	0.0070	
Forward transconductance ^a	g_{fs}	$V_{DS} = -10\text{ V}$, $I_D = -15\text{ A}$	-	75	-	S
Dynamic ^b						
Input capacitance	C_{ISS}	$V_{DS} = -10\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	-	7080	-	μF
Output capacitance	C_{OSS}		-	1000	-	
Reverse transfer capacitance	C_{RSS}		-	1110	-	
Total gate charge	Q_g	$V_{DS} = -10\text{ V}$, $V_{GS} = -8\text{ V}$, $I_D = -35.1\text{ A}$	-	157.2	236	nC
		$V_{DS} = -10\text{ V}$, $V_{GS} = -4.5\text{ V}$, $I_D = -35.1\text{ A}$	-	72.2	110	
Gate-source charge	Q_{gs}		-	17.7	-	
Gate-drain charge	Q_{gd}		-	22	-	
Gate resistance	R_g	$f = 1\text{ MHz}$	0.3	1.5	3	Ω
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10\text{ V}$, $R_L = 0.36\text{ }\Omega$, $I_D \cong -28.1\text{ A}$, $V_{GEN} = -10\text{ V}$, $R_g = 1\text{ }\Omega$	-	20	40	ns
Rise time	t_r		-	28	56	
Turn-off delay time	$t_{d(off)}$		-	80	160	
Fall time	t_f		-	25	50	
Turn-on delay time	$t_{d(on)}$		-	40	80	
Rise time	t_r	$V_{DD} = -10\text{ V}$, $R_L = 0.36\text{ }\Omega$, $I_D \cong -28.1\text{ A}$, $V_{GEN} = -4.5\text{ V}$, $R_g = 1\text{ }\Omega$	-	60	120	
Turn-off delay time	$t_{d(off)}$		-	100	200	
Fall time	t_f		-	70	140	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	-54.8	A
Pulse diode forward current	I_{SM}		-	-	-200	
Body diode voltage	V_{SD}	$I_S = -5\text{ A}$, $V_{GS} = 0\text{ V}$	-	-0.66	-1.2	V
Body diode reverse recovery time	t_{rr}	$I_F = -28.1\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$	-	20	40	ns
Body diode reverse recovery charge	Q_{rr}		-	9.5	19	nC
Reverse recovery fall time	t_a		-	11.5	-	ns
Reverse recovery rise time	t_b		-	8.5	-	

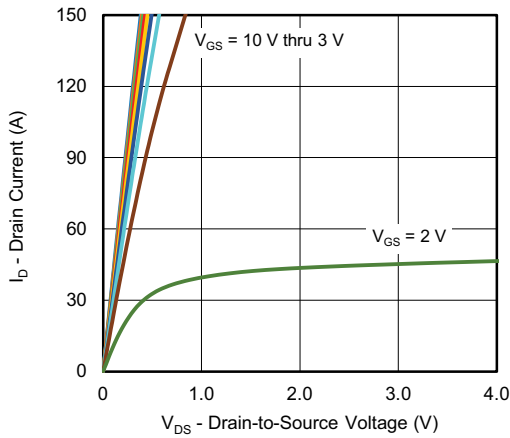
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

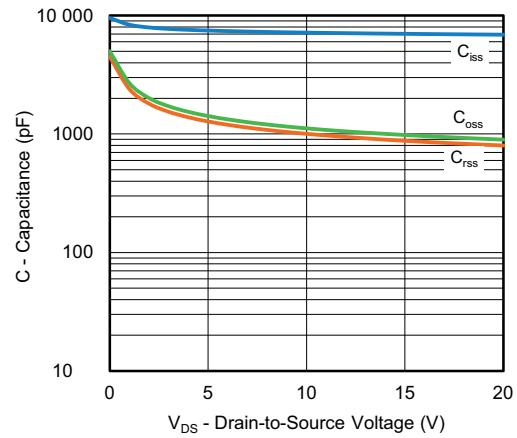
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



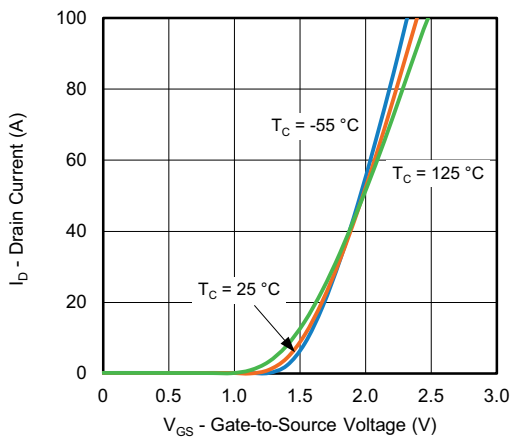
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



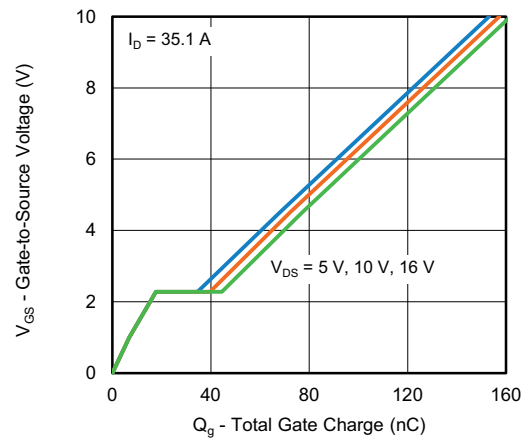
Output Characteristics



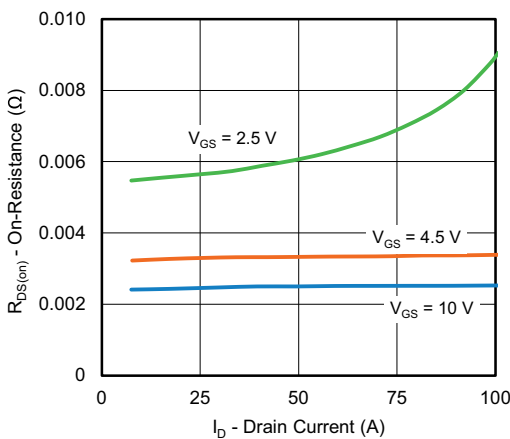
Transfer Characteristics



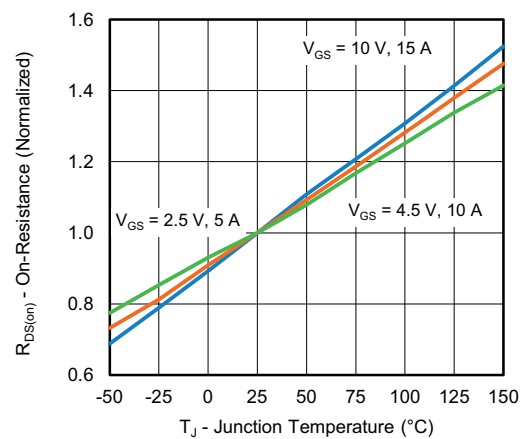
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



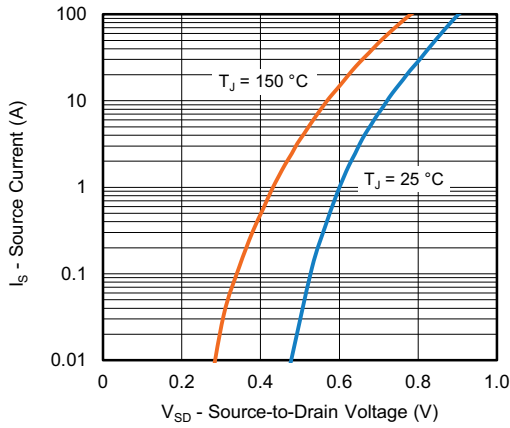
Gate Charge



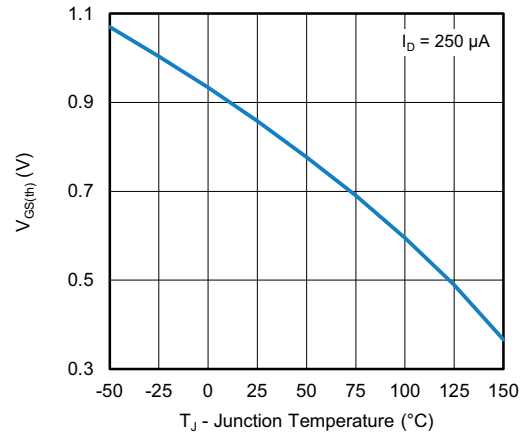
On-Resistance vs. Junction Temperature



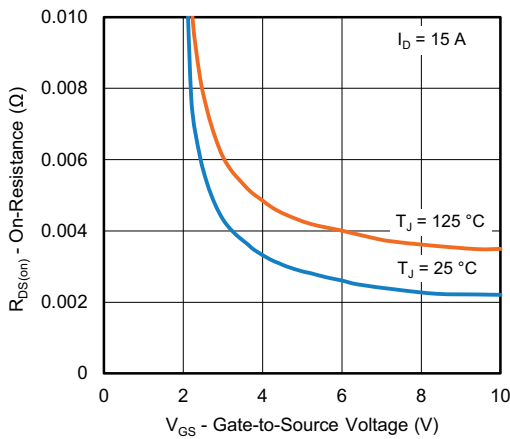
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



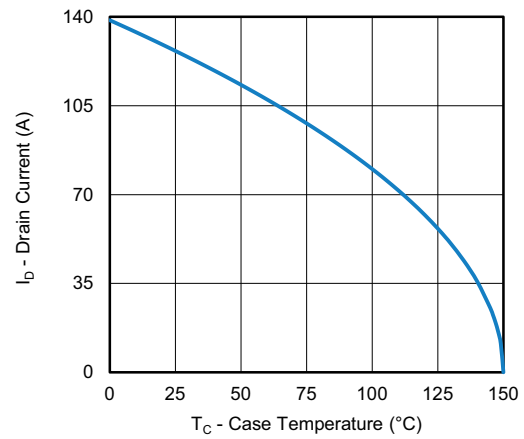
Source-Drain Diode Forward Voltage



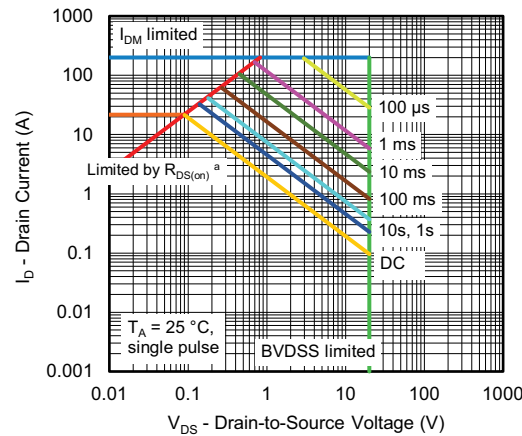
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



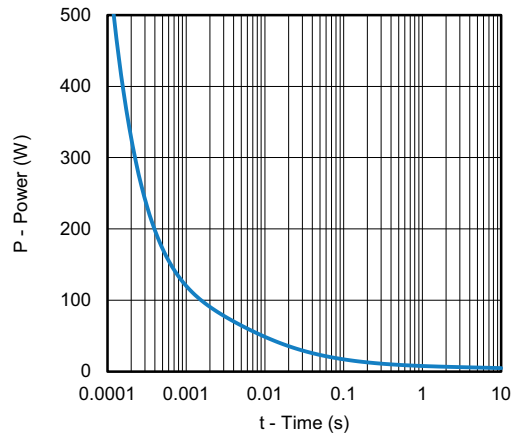
Safe Operating Area, Junction-to-Ambient

Note

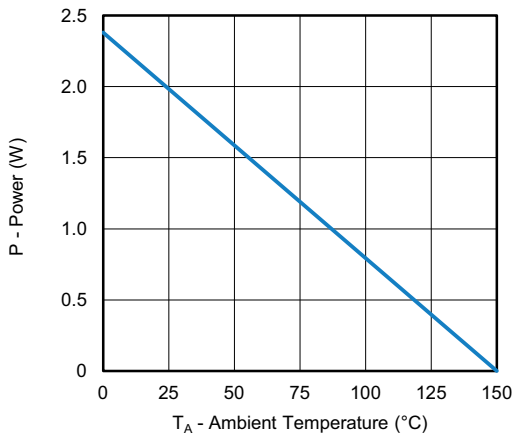
a. VGS > minimum VGS at which RDS(on) is specified



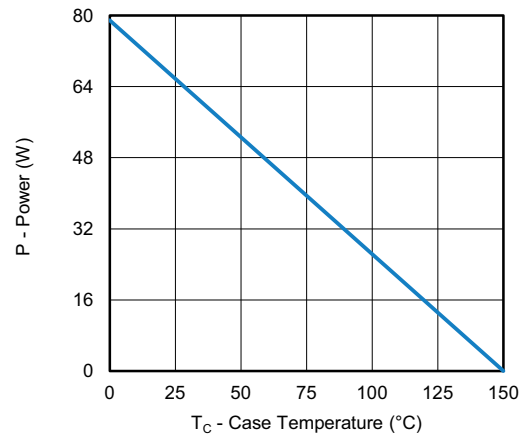
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



Single Pulse Power, Junction-to-Ambient

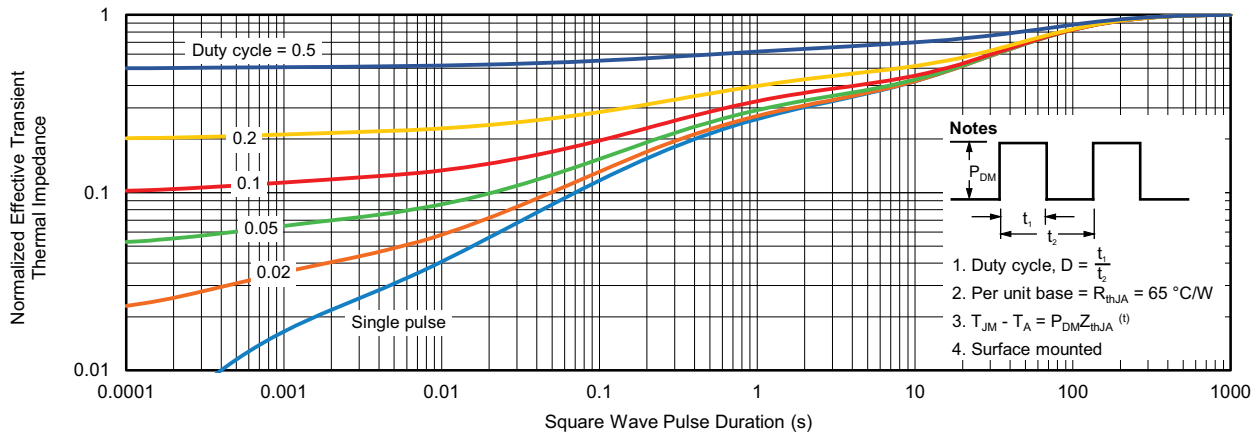


Power, Junction-to-Case

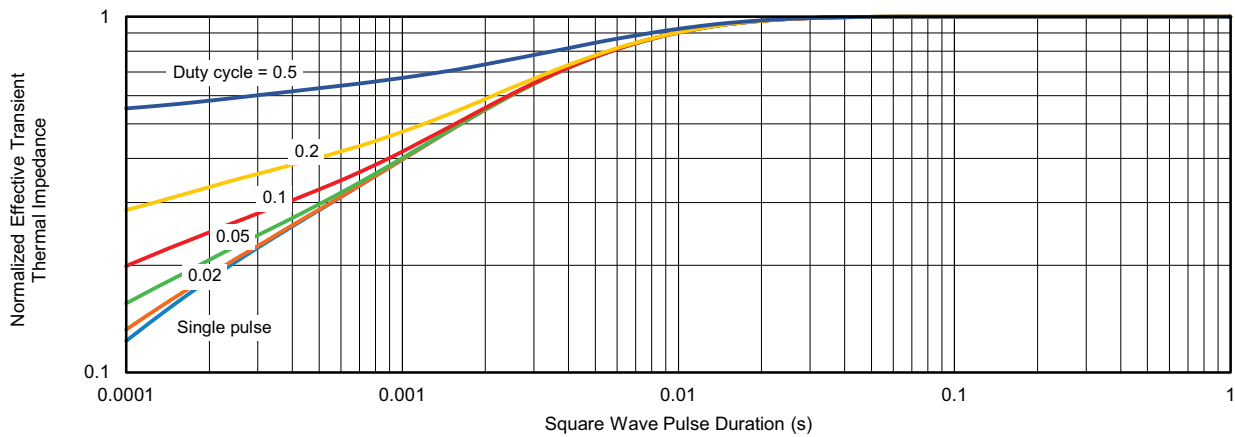
Note

a. The power dissipation P_D is based on $T_J \text{ max.} = 150 \text{ }^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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Case Outline for PowerPAK® 1212-8S



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.67	0.75	0.83	0.026	0.030	0.033
A1	0.00	-	0.05	0.000	-	0.002
A3	0.20 ref.			0.008 ref		
b	0.25	0.30	0.35	0.010	0.012	0.014
D	3.20	3.30	3.40	0.126	0.130	0.134
D1	2.15	2.25	2.35	0.085	0.089	0.093
E	3.20	3.30	3.40	0.126	0.130	0.134
E1	1.60	1.70	1.80	0.063	0.067	0.071
e	0.65 bsc.			0.026 bsc.		
K	0.76 ref.			0.030 ref.		
K1	0.41 ref.			0.016 ref.		
L	0.33	0.43	0.53	0.013	0.017	0.021
Z	0.525 ref.			0.021 ref.		

ECN: C20-0862-Rev. B, 20-Jul-2020
 DWG: 6008

RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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